Lam Research Corporation Announces Qualification Of TeresTM For 0.18 Micron Copper CMP At TSMC

Lam Research Corporation Announces Qualification Of Teres™ For 0.18 Micron Copper CMP At TSMC FREMONT, Calif., October 18, 1999 - Lam Research Corporation (Nasdaq: LRCX) today announced that it's Teres integrated CMP and post-CMP clean system has been qualified for 0.18 micron copper CMP processes at Taiwan Semiconductor Manufacturing Company (TSMC). This success is the result of a joint development project between the two companies that began in March of this year. Teres is the first system to be qualified for copper CMP at TSMC and is now the foundry's production tool of record for copper processes.

According to Dr. S. Y. Chiang, vice president of Research and Development at TSMC, "Teres met or exceeded our specifications for dishing, erosion, total metal loss, and resistance non-uniformity. We are quite pleased with its performance and will be ramping quickly to copper production."

In addition, Lam's team exceeded TSMC's start-up requirement. Daniel Liao, Lam's vice president of Asia Pacific Operations, commented, "This success for copper CMP at Taiwan's largest foundry soundly demonstrates Teres' exceptional current-production and next-generation capabilities."

For copper CMP, the Teres system's innovative Linear Planarization Technology™ (LPT™) delivers optimized uniformity and planarity while simultaneously minimizing dishing, erosion, and total oxide and metal loss. Conversely, rotary systems can be optimized to achieve good results only on a few selected parameters, but cannot match Teres' performance across all parameters on a single wafer. Teres also features an integrated Synergy Integra™ post-CMP clean module with the Performa™ feature set that provides proprietary chemistries for copper clean.

"Safe Harbor" Statement Under the Private Securities Litigation Act of 1995: This press release contains certain forward-looking statements which are subject to the Safe Harbor provisions created by the Private Securities Litigation Reform Act of 1995. Such forward-looking statements may relate to anticipated product shipments under existing orders, shipment schedules, the prospective demand for the company's products, acceptance and competitiveness of the company's products and market transition to new processes. Such statements are based on current expectations and are subject to risks, uncertainties, and changes in condition, such as fluctuations in the semiconductor equipment market affecting existing orders and shipment schedules, and other risks detailed in documents filed with the Securities and Exchange Commission, including specifically the report on Form 10-K for the year ended June 30, 1999 and the Form 10-Q for the quarter ended March 30, 1999. The company undertakes no obligation to update the information in this Press Release.

Lam Research Corporation is a leading supplier of front-end wafer processing equipment and services to the worldwide semiconductor manufacturing industry. The company's common stock trades on the Nasdaq National Market under the symbol LRCX. Lam's World Wide Web address is http://www.lamrc.com.

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